

PRODUCT PROFILE

ELECTROLOY HALIDE FREE NO CLEAN LEAD FREE WIRE

Product Name

**#81 FLUX CORED SOLDER
-LEAD FREE ALLOY-Sn99.0/Ag0.3/Cu0.7**

Product Code

EM#81-315W

The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assure legal responsibility. Users should undertake sufficient verification and testing to determine the suitability for their own particular purpose of any information or products referred to herein. No warranty of fitness for a particular purpose is made. Properties are typical and not to be used as specifications.

DOC CATEGORY: 3

PF – EM#81-315W – 04032009 – REV.A – Page 1 of 4

PRODUCT DESCRIPTION

EM#81-315W* is a halide free no clean cored flux lead free wire with alloy composition 99.0%Tin, 0.3%Silver and 0.7%Copper. This type of cored flux wire provides fast wetting and leaves lowest and clear flux residue. This is a RoHS compliance lead free solder wire.

* Patent No : US 5527628

CHEMICAL COMPOSITION OF ALLOY

Quality of Electroloy's EM#81-315W lead free solder wire in terms of composition of alloy is controlled strictly under Electroloy's Lead Free Specification LF-315.

Elements		Specification (%wt/wt)
Tin	Sn	Remainder
Lead	Pb	Max 0.050
Aluminium	Al	Max 0.005
Antimony	Sb	Max 0.050
Arsenic	As	Max 0.030
Bismuth	Bi	Max 0.050
Copper	Cu	0.6 – 0.8
Iron	Fe	Max 0.010
Zinc	Zn	Max 0.003
Cadmium	Cd	Max 0.002
Silver	Ag	0.2 – 0.4
Nickel	Ni	Max 0.010
Indium	In	Max 0.050
Gold	Au	Max 0.050

The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assure legal responsibility. Users should undertake sufficient verification and testing to determine the suitability for their own particular purpose of any information or products referred to herein. No warranty of fitness for a particular purpose is made. Properties are typical and not to be used as specifications.

CHEMICAL COMPOSITION OF FLUX

The standard flux content for this type of solder wire is 2.5 +/- 0.2%. However, other percentages of flux are available upon request. The range for the flux percentage is 2.2% – 3.3%.

FEATURES OF CORED FLUX

Flux Cored Type	Features	Cleaning Method
No-Clean Halide Free EM#81	Halide free with lowest and clear flux residue suited for no-clean hand soldering assemblies. Exhibit fast wetting characteristics. Widely and most popular choice for assemblies requiring no-clean, clear residue characteristics. Suitable for use on different alloys.	No-clean

CHARACTERISTICS OF CORED FLUX EM#81

Physical Properties and Reliability Data	Specification	Test Method	Result (Typical)
Flux Type	-	-	Halide Free No Clean
Class Type	Refer to J-STD-004	-	ROL0
Color/Appearance	-	-	Clear
Odor	-	-	Mild
Halide Content (%) (Chloride and Bromide)	Max 0.0 %	JIS Z 3197, Method 8.1.4.2.1	0.00 %
Corrosion Test	Pass	J-STD-004, IPC-TM-650, Method 2.6.15	Pass
SIR,IPC(Typical) 85°C / 85% RH After 168 hours	Min $1 \times 10^8 \Omega$	J-STD-004, IPC-TM-650, Method 2.6.3.3	$\geq 1.0 \times 10^{11} \Omega$
Spreading (%)	Min 65% Lead Free Solder (JIS 3283:2006)	JIS Z 3197, Method 8.3.1.1	$\geq 80\%$

The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assure legal responsibility. Users should undertake sufficient verification and testing to determine the suitability for their own particular purpose of any information or products referred to herein. No warranty of fitness for a particular purpose is made. Properties are typical and not to be used as specifications.

PHYSICAL APPEARANCE

Electroloy's solder wire exhibits a shinning appearance and in grey uniform color. A wide range of diameter for the wire is available, 0.2– 2.4mm (+/-0.05mm) , 2.5mm – 3.5mm (+/-0.1mm) , 3.6mm – 4.5mm (+/-0.2mm) and $\geq 4.6\text{mm}$ (+/-0.3mm).

CLEANING

The flux residue is not conductive and is not corrosive to metal parts. Therefore, cleaning is not required in most application.

APPLICATION

Solder iron tip temperature should be between 350 – 430°C. Hold the solder iron tip at a 45° to 60° angle with work surface. The solder iron should contact both the component lead and PCB pad surface.

PACKAGING

Each spool of solder wire is approximately 0.5kg or 1.0kg and shall be secured by paper and rolling tape. The solder wire shall be packed in carton boxes of about 10kg per box. Other special size and packaging requirement can be requested. The traceable information will be shown on the box such as vendor's name, alloy composition, net weight and lot number.

DELIVERY

Each shipment shall be accompanied with Certificate of Analysis for each lot, which indicate the amount of constituents and impurities.

STORAGE AND SHELF LIFE

Electroloy's EM#81-315W lead free solder wire has limited shelf life which is 18 months from the date of manufactured when handled properly. Dry and non-corrosive storage environment is needed to minimize the wires from further oxidation. Ensure that the packaging is not damaged and the wires are not exposed to dust and other foreign materials.

HEALTH AND SAFETY

Refer to the MSDS for guidance on safety and health issues.

The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assure legal responsibility. Users should undertake sufficient verification and testing to determine the suitability for their own particular purpose of any information or products referred to herein. No warranty of fitness for a particular purpose is made. Properties are typical and not to be used as specifications.